

Type number	Package	Package description	Total product weight
PZU5.6B1	SOD323F	SOD323F	3.78317 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
934059793115	12	1	260	30 s	1	235	20 s	3	D-22529 HAMBURG, Germany; Dongguan, China	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.05000	100.00000	1.32164
		subTotal		0.05000	100.00000	1.32164
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	1.43420	94.98000	37.90995
		Iron (Fe)	7439-89-6	0.03850	2.55000	1.01780
		Lead (Pb)	7439-92-1	0.00045	0.03000	0.01197
		Misc. Phosphor compounds (generic)	7723-14-0	0.00226	0.15000	0.05987
		Zinc (Zn)	7440-66-6	0.00302	0.20000	0.07983
	Pure metal layer	Silver (Ag)	7440-22-4	0.03156	2.09000	0.83419
		subTotal		1.51000	100.00000	39.91361
Mould Compound	Filler	Silica fused	60676-86-0	1.60714	75.10000	42.48131
	Pigment	Carbon black	1333-86-4	0.00642	0.30000	0.16970
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	0.37450	17.50000	9.89911
		Phenol Formaldehyde resin (generic)	9003-35-4	0.15194	7.10000	4.01621
		subTotal		2.14000	100.00000	56.56633
Post-Plating	Impurity	Antimony (Sb)	7440-36-0	0.00001	0.01000	0.00021
		Bismuth (Bi)	7440-69-9	0.00002	0.02000	0.00042
		Iron (Fe)	7439-89-6	0.00001	0.01000	0.00021
		Lead (Pb)	7439-92-1	0.00001	0.01000	0.00021
	Tin solder	Tin (Sn)	7440-31-5	0.07996	99.95000	2.11357
		subTotal		0.08000	100.00000	2.11462
Wire	Pure metal	Copper (Cu)	7440-50-8	0.00317	100.00000	0.08369
		subTotal		0.00317	100.00000	0.08369

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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